

Title (en)  
DEVICE AND METHOD FOR CUTTING A SOLID SUBSTRATE

Title (de)  
VORRICHTUNG UND VERFAHREN ZUM SCHNEIDEN EINES FESTEN SUBSTRATS

Title (fr)  
DISPOSITIF ET PROCÉDÉ POUR COUPER UN SUBSTRAT SOLIDE

Publication  
**EP 4029670 A1 20220720 (EN)**

Application  
**EP 21151771 A 20210115**

Priority  
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Abstract (en)  
The invention pertains to a device for cutting a solid substrate, preferably a solid semiconductor substrate for use as wafer material, comprising at least two guiding rollers and a cutting wire guided by the at least two guiding rollers forming a wire web between them, and comprising moving means for effecting a relative movement between a solid substrate and the guiding rollers to introduce the solid substrate into the wire web for cutting the solid substrate into a multitude of substrate slices, wherein the wire web is of sufficient size to allow cutting of a solid substrate with a cross section extension of at least 25 cm, wherein the device comprises at least three guiding rollers arranged preferably in triangular form wherein the cutting wire is guided by the at least three guiding rollers and the solid substrate can be introduced by the moving means into the wire web between a first guiding roller and a second guiding roller of the at least three guiding rollers for cutting, and wherein the device comprises pivoting means for alternately pivoting the solid substrate about a longitudinal axis of the solid substrate during cutting and/or for alternately pivoting the guiding rollers about a common axis parallel to their longitudinal axes during cutting. The invention further pertains to a corresponding method.

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Citation (applicant)  
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